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Silicon NPN Epitaxial Planar

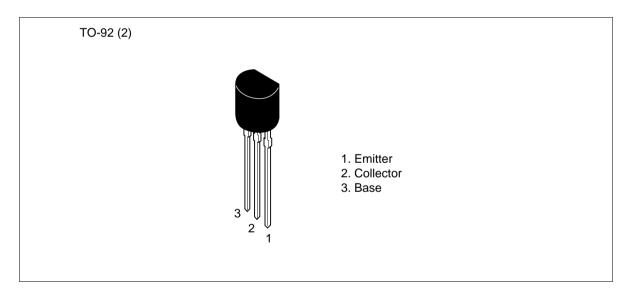


ADE-208-1046 (Z) 1st. Edition Mar. 2001

Application

- 2SC460 high frequency amplifier, mixer
- www.DataS2SC461/VHF amplifier, mixer

Outline



Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	2SC460	2SC461	Unit
Collector to base voltage	V _{CBO}	30	30	V
Collector to emitter voltage	V _{CEO}	30	30	V
Emitter to base voltage	V _{EBO}	5	5	V
Collector current	Ι _c	100	100	mA
Collector power dissipation	Pc	200	200	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

vww.DataSheet4U.com



Electrical Characteristics (Ta = 25°C)

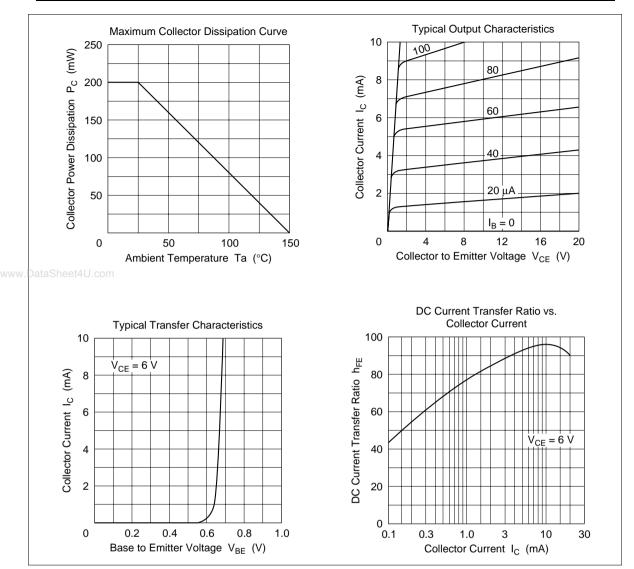
		2SC4	60		2SC4	61			
Item	Symbol	Min	Тур	Max	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	30	_	_	30	_		V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	30	_	_	30	—	_	V	$I_c = 1 \text{ mA}, R_{BE} =$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	5	—	—	5	—	_	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	—	—	0.5	—		0.5	μA	$V_{CB} = 18 \text{ V}, \text{ I}_{E} = 0$
Emitter cutoff current	I _{EBO}	—	—	0.5	—	—	0.5	μA	$V_{EB} = 2 V, I_{C} = 0$
Base to emitter voltage	V_{BE}	—	0.63	0.75	—	0.63	0.75	V	$V_{ce} = 12 \text{ V}, \text{ I}_{c} = 2 \text{ mA}$
DC current transfer ratio	h_{FE}^{*1}	35	_	200	35	_	200		$V_{ce} = 12 \text{ V}, \text{ I}_{c} = 2 \text{ m/s}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	0.6	1.1	_	0.6	1.1	V	$I_{c} = 10 \text{ mA}, I_{B} = 1 \text{ m/}$
Gain bandwidth product	f _T	—	230		—	230	—	MHz	$V_{ce} = 12 \text{ V}, \text{ I}_{c} = 2 \text{ mA}$
Collector output capacitance	C_{ob}	—	1.8	3.5	_	1.8	3.5	pF	$V_{CB} = 10 \text{ V}, \text{ I}_{E} = 0,$ f = 1 MHz
10.7 MHz power gain	PG	26	29	—	_	—		dB	$V_{ce} = 6 V, I_e = -1 mA$ f = 10.7 MHz
100 MHz power gain	PG	—	_	_	13	17	_	dB	$V_{ce} = 6 V, I_e = -1 mA$ f = 100 MHz
Noise figure	NF		2.0		_	_	_	dB	$V_{CE} = 6 \text{ V}, \text{ I}_{E} = -1 \text{ mA}$ f = 1MHz R _g = 500\Omega

Α	В	С	
35 to 70	60 to 120	100 to 200	

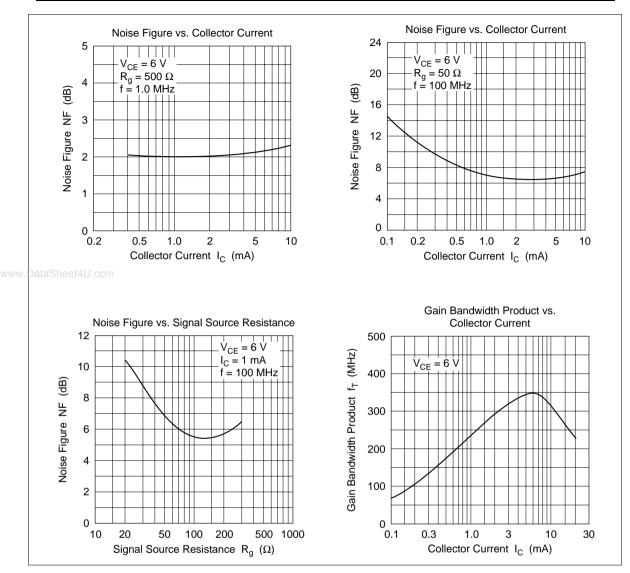
Item	Symbol	f	2SC460A, 2S461A	2SC460B, 2SC461B	2SC460C, 2SC461C	Unit
Input admittance	yie	455 kHz	0.58 + j0.074	0.42 + j0.068	0.30 + j0.051	mS
		4.5 MHz	0.65 + j0.79	0.50 + j0.7	0.35 + j0.57	-
		10.7 MHz	0.91 + j2.0	0.61 + j1.9	0.39 + j1.3	-
		100 MHz	7.4 + j14	5.6 + j12	3.8 + j6.0	-
Reverse transfer admittance	yre	455 kHz	-j0.003	-j0.003	-j0.003	mS
		4.5 MHz	-j0.04	-j0.04	-j0.04	-
		10.7 MHz	–j0.13	–j0.13	–j0.13	-
		100 MHz	-j1.0	—j1.0	—j1.0	-
Forward transfer admittance	yfe	455 kHz	38 – j0.1	37 – j0.1	37 – j0.2	mS
		4.5 MHz	35 – j1.0	35 – j1.2	34 – j1.8	
		10.7 MHz	34 – j2.5	34 – j2.5	33 – j4.5	-
		100 MHz	28 – j20	28 – j19	20 – j19	
Output admittance	yoe	455 kHz	0.0098 + j0.009	0.013 + j0.009	0.016 + j0.012	mS
		4.5 MHz	0.02 + j0.09	0.023 + j0.092	0.03 + j0.10	-
		10.7 MHz	0.11 + j0.4	0.11 + j0.4	0.12 + j0.4	
		100 MHz	0.40 + j1.7	0.50 + j2.0	0.83 + j2.0	-

Small Signal y Parameters ($V_{CE} = 6 V$, $I_C = 1 mA$, Emitter Common)

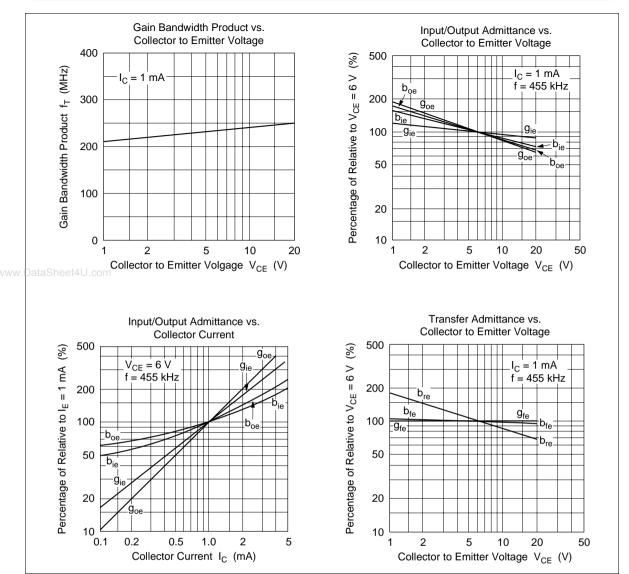




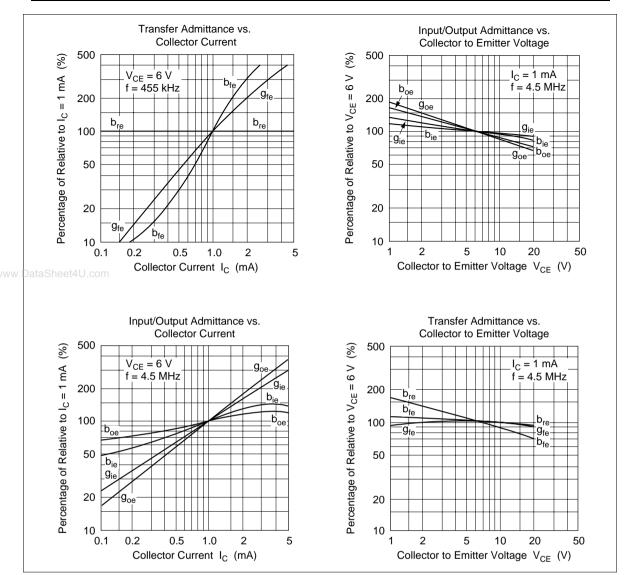




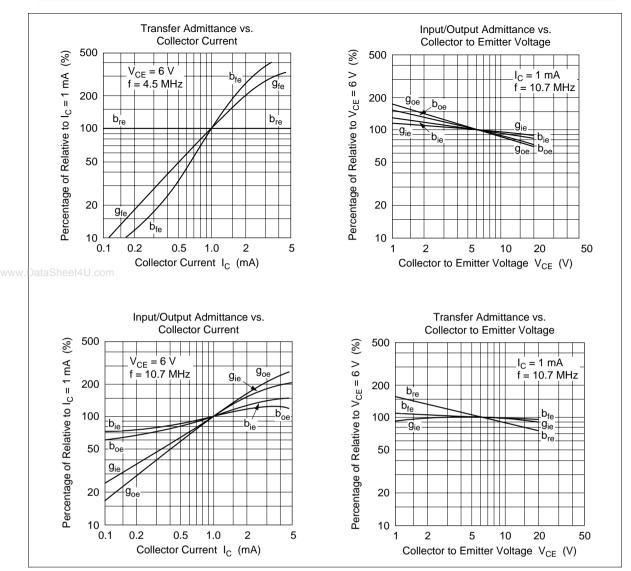




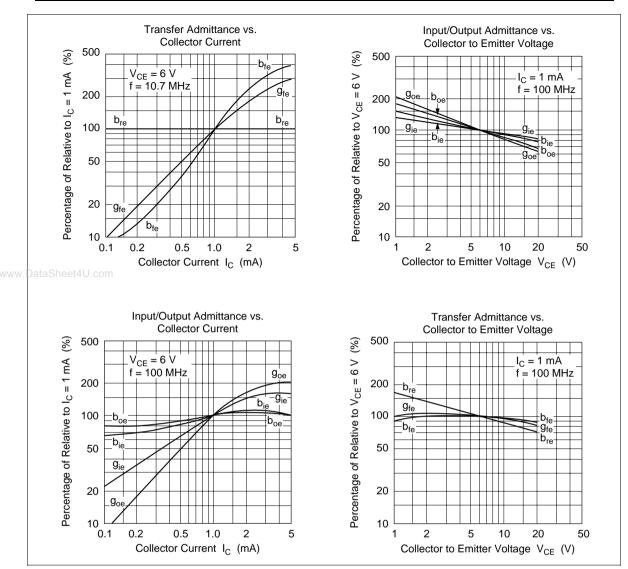




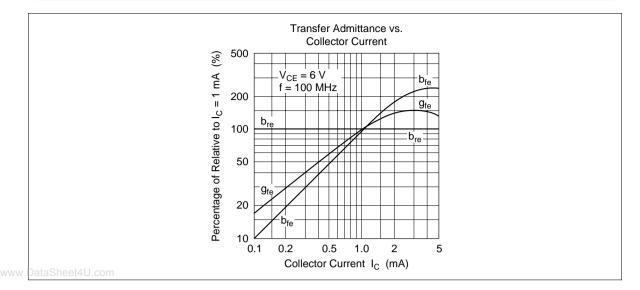




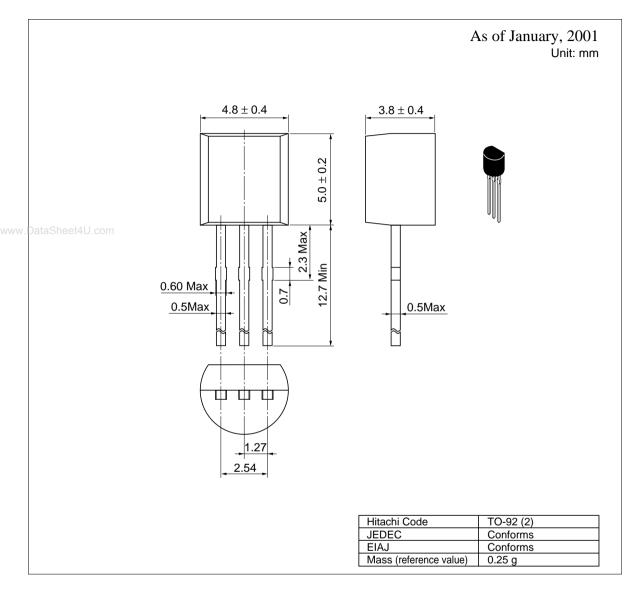








Package Dimensions





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